

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims of the application:

### Listing of Claims:

1. (Currently Amended) A system mounting a semiconductor die within a package comprising:
  - a mounting surface;
  - an X-lead frame coupled to said mounting surface; and
  - said semiconductor die, wherein said semiconductor die is disposed between and held in place by said mounting surface and said X-lead frame without bonding to said mounting surface and without bonding to said X-lead frame.
2. (Original) A package as described in Claim 1 wherein said semiconductor die is a power enhancement mode JFET having a surface region defining a source, a surface region defining a drain and a surface region defining a gate.

3. (Original) The power semiconductor package of Claim 2 wherein electrical coupling between said drain and said X-lead frame is realized by angular projections of said X-lead frame contacting said drain.

4. (Original) The power semiconductor package of Claim 2 wherein said X-lead frame is bonded to a first terminal disposed on said mounting surface.

5. (Original) The power semiconductor package of Claim 2 wherein a second terminal disposed on said mounting surface is electrically connected to said source.

6. (Original) The power semiconductor package of Claim 2 wherein a third terminal disposed on said mounting surface is electrically connected to said gate.

7. (Original) The semiconductor package of Claim 1, wherein said package is sized and shaped to conform to an S08 configuration.

8. (Original) The semiconductor package of Claim 1, wherein said first terminal is a solid terminal spanning the full width of four leads and the spaces between four leads on one side of said S08 package.

9. (Original) The semiconductor package of Claim 1, wherein said second terminal is a solid terminal spanning a width of three leads and the spaces between three leads on a side of said S08 package opposite to said first terminal.

10. (Original) The semiconductor package of Claim 1, wherein said third terminal is a solid terminal spanning a width of a single lead on a side of said S08 package opposite to said first terminal.

11 through 22. (Cancelled)

23. (New) The semiconductor package of Claim 1 wherein said X-lead frame comprises at least one angular extension configured to make physical and electrical contact with said semiconductor die.

24. (New) The semiconductor package of Claim 23 wherein said mounting surface comprises at least one source pad configured to make mechanical and electrical contact with said semiconductor die.

25. (New) The semiconductor package of Claim 1 wherein said mounting surface comprises at least one source pad configured to make mechanical and electrical contact with said semiconductor die.